



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten up The World With LED!*



ISO/TS 16949:2009

BS-EM ISO 14001:2004

QC 900000 IECQ HSP98

## PRODUCT DATASHEET

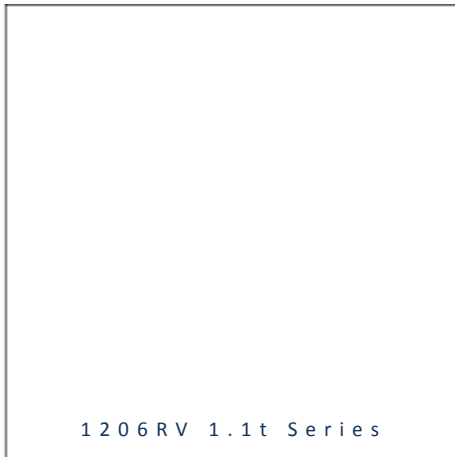


- ▶ PCB Reverse Mount
- ▶ 1206RV 1.1t Series
- ▶ Green (525nm)

**NOG09S75RV**



Release Date: 16 March 2015 Version: A1.3



1206RV 1.1t Series

### 1206RV 1.1t Series



#### FEATURES:

- **Package:** PCB Reverse Mount SMT Package
- **Forward Current:** 5mA
- **Forward Voltage (typ.):** 3.4V
- **Luminous Intensity (typ.):** 250mcd @5mA
- **Colour:** Green
- **Wavelength:** 525nm
- **Viewing angle:** 130°
- **Materials:**
  - Die: InGaN
  - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+90°C
- **ESD:** 150V
- **Grouping parameters:**
  - Forward voltage
  - Luminous intensity
  - Dominant Wavelength
- **Soldering methods:** Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with 2000/reel, ø180mm (7")

#### APPLICATIONS:

- Backlighting
- Indication Light
- Switch light

**CHARACTERISTICS:**


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## Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	$I_F$	25	mA
Peak Forward Current Duty 1/10@10KHz	$I_{FP}$	100	mA
Reverse Current @5V	$I_R$	50	$\mu$ A
Power Dissipation	PD	75	mW
Electrostatic Discharge	ESD	150	V
Operating Temperature	$T_{OPR}$	-40~+85	°C
Storage Temperature	$T_{STG}$	-40~+90	°C

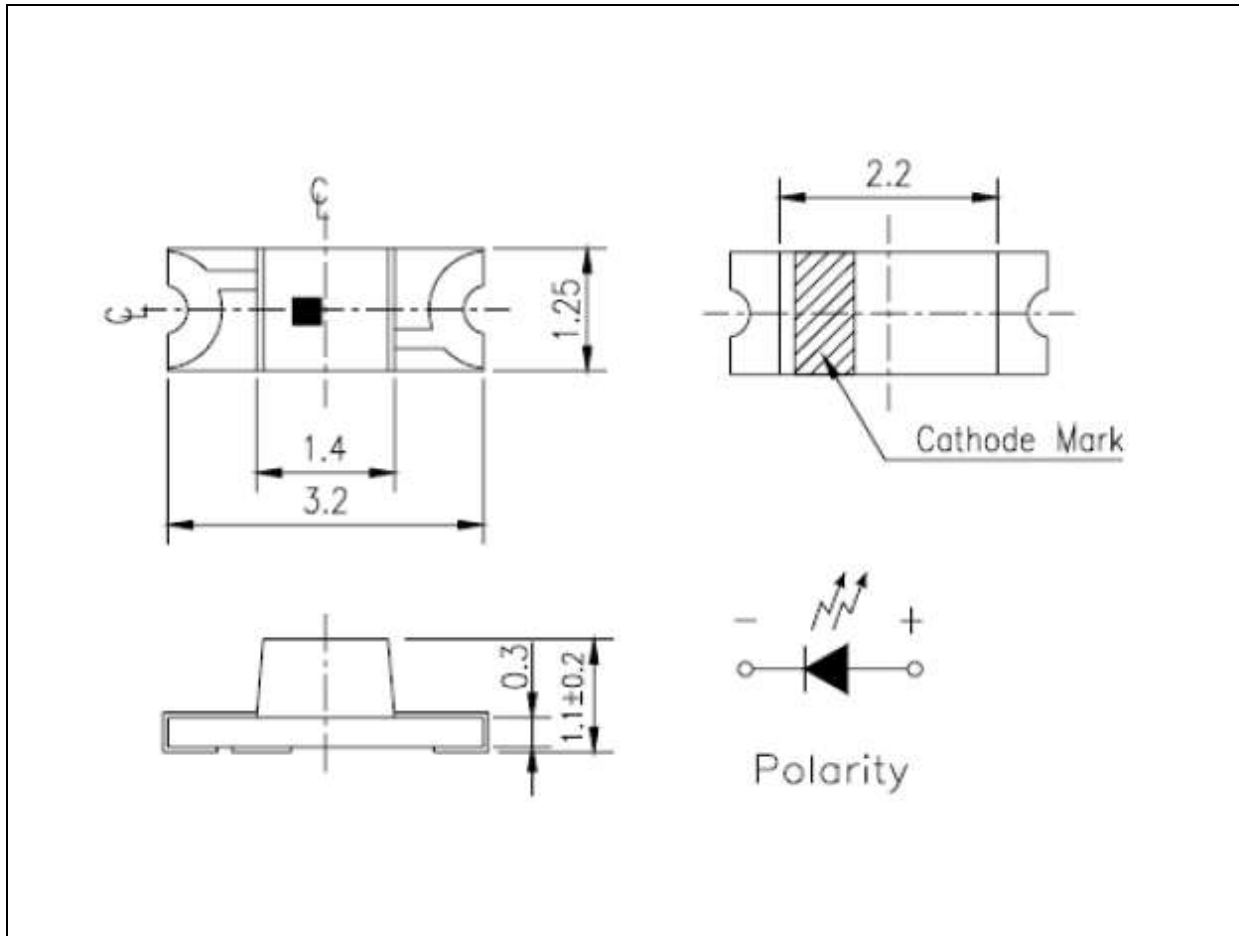
## Electrical &amp; Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	$V_F$	2.7	---	3.7	V	$I_F=5mA$
Luminous Intensity	$I_V$	140	---	360	mcd	$I_F=5mA$
Dominant Wavelength	$\lambda_D$	520	---	535	nm	$I_F=5mA$
Peak Wavelength	$\lambda_P$	---	518	---	nm	$I_F=5mA$
Spectral Line Half Bandwidth	$\Delta \lambda$	---	35	---	nm	$I_F=5mA$
Viewing Angle	$2\theta_{1/2}$	---	130	---	deg	$I_F=5mA$

1. Luminous intensity ( $I_V$ )  $\pm 15\%$ , Forward Voltage ( $V_F$ )  $\pm 0.1V$ , Viewing angle( $2\theta_{1/2}$ )  $\pm 5\%$
2. IS standard testing

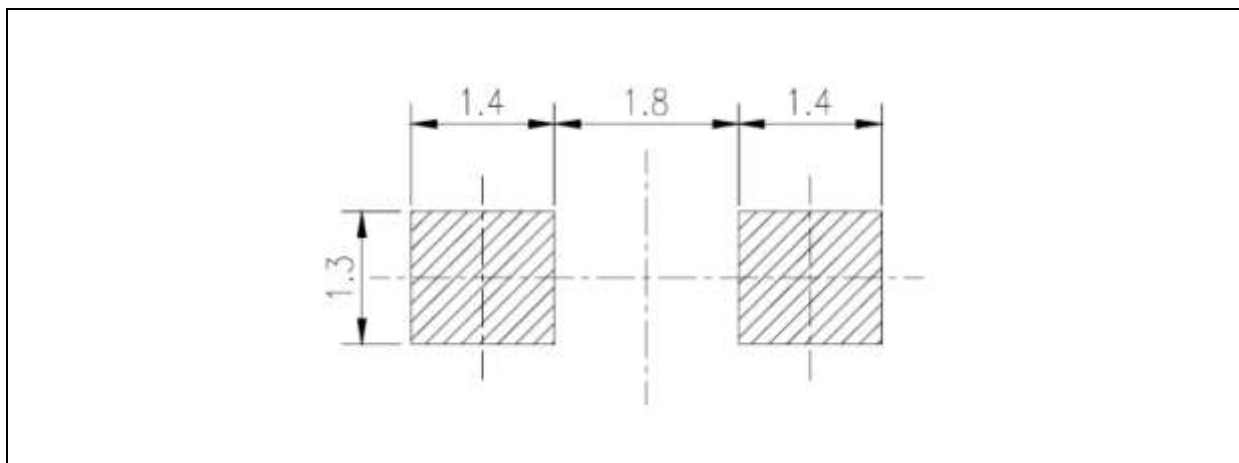
## OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.2$ mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5^\circ$ .

**BINNING GROUPS:**

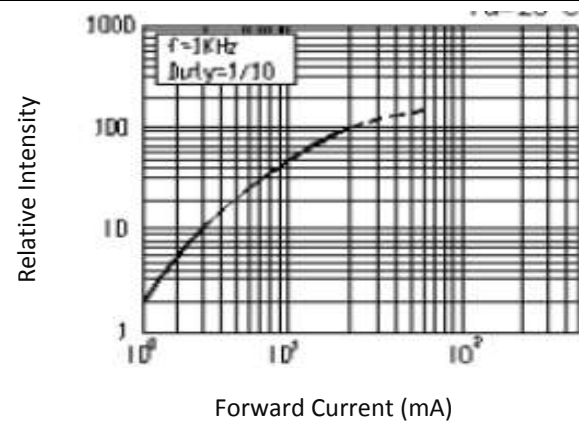
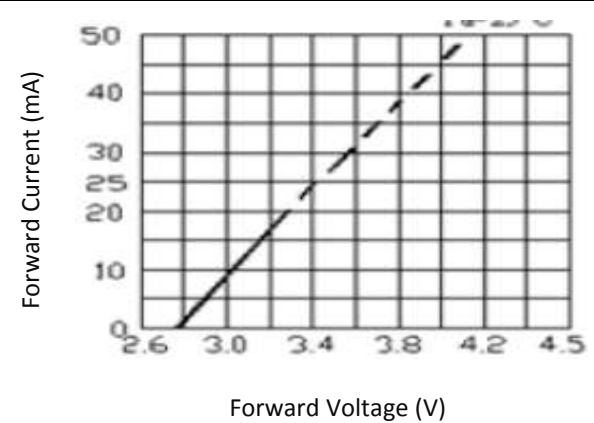
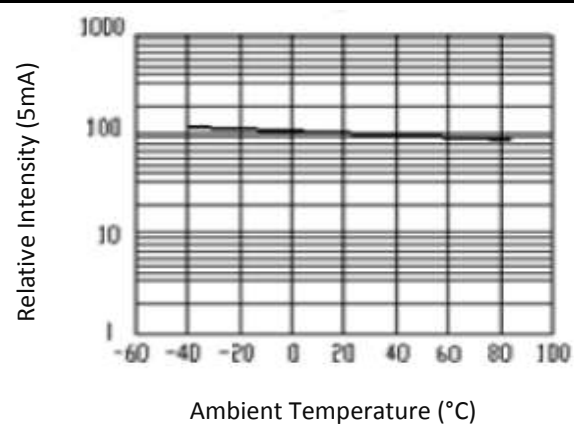
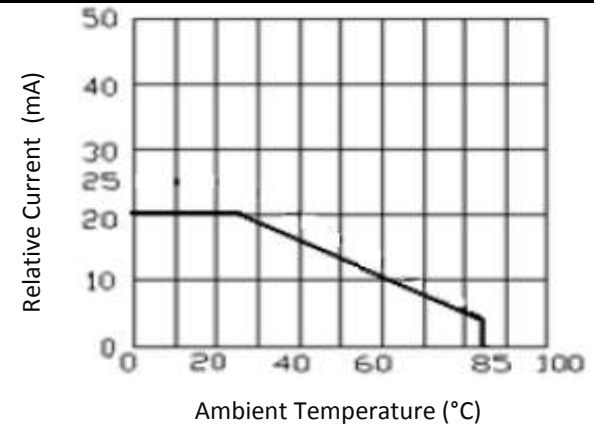
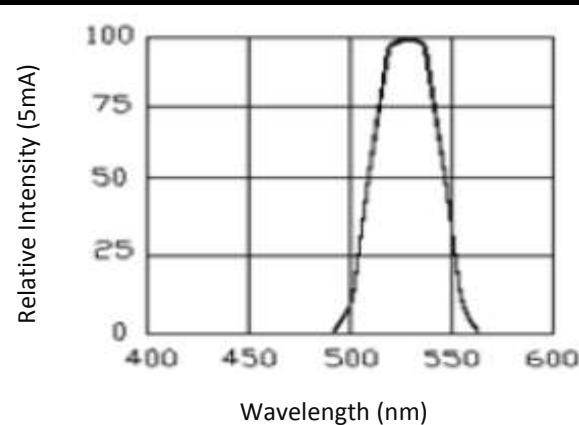
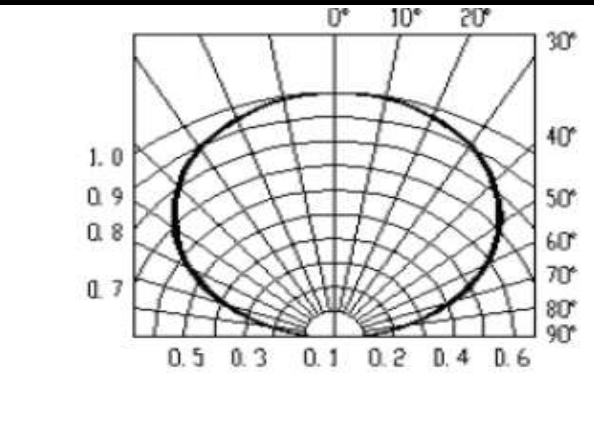

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 Luminous Intensity Classifications ( $I_F = 5\text{mA}$ ):

Code	Min.	Max.	Unit
R2	140	180	mcd
S1	180	225	
S2	225	285	
T1	285	360	

 Dominant Wavelength Classifications ( $I_F = 5\text{mA}$ ):

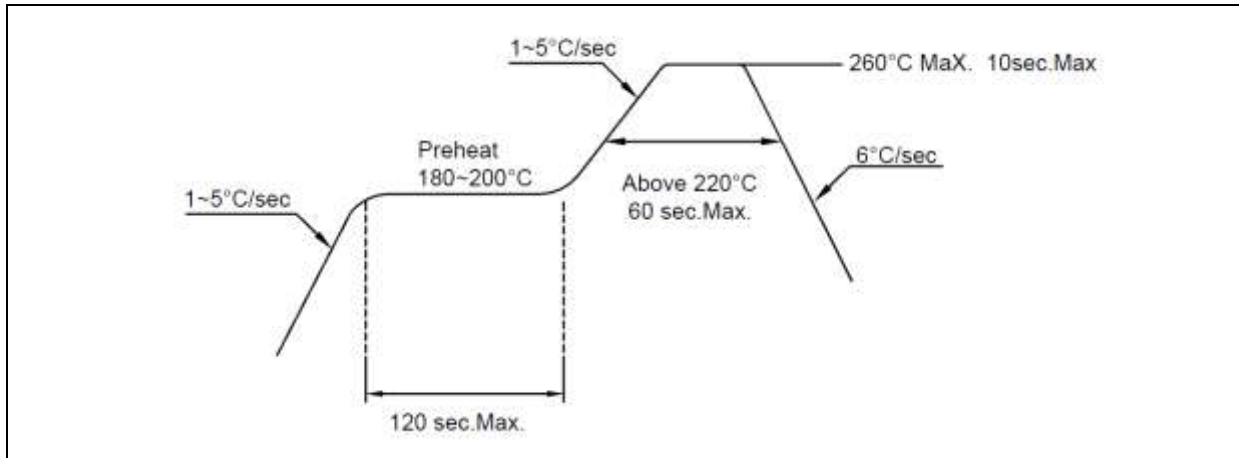
Code	Min.	Max.	Unit
X	520	525	nm
Y	525	530	
Z	530	535	

**ELECTRO-OPTICAL CHARACTERISTICS:**
**Relative Intensity v.s. Forward Current**

**Forward Current v.s. Forward Voltage**

**Relative Intensity v.s. Temperature**

**Relative Forward Current v.s. Temperature**

**Relative Intensity v.s. Wavelength**

**Directive Radiation**


## RECOMMENDED SOLDERING PROFILE:

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Lead-free Solder:

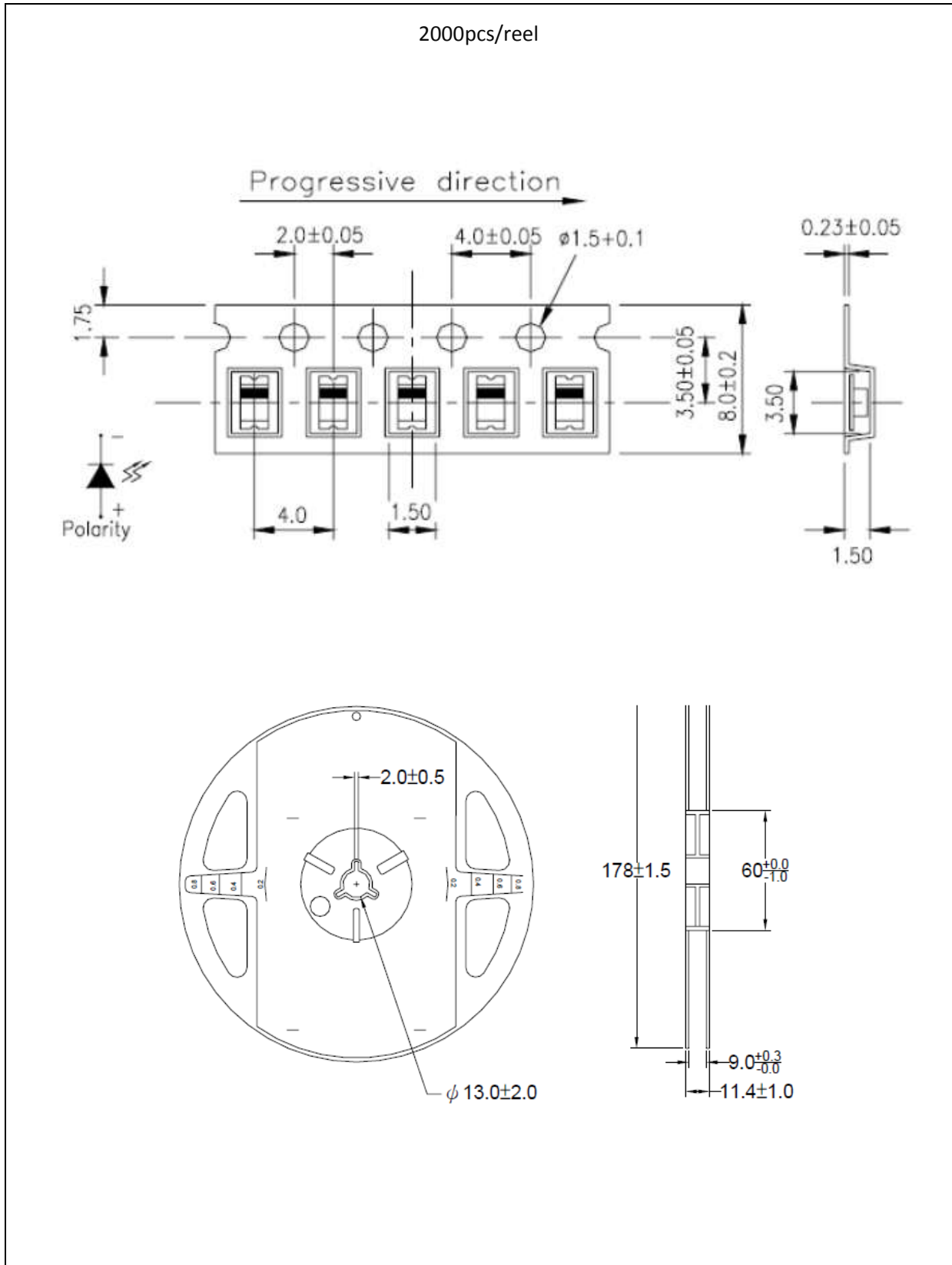


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

**PACKING SPECIFICATION:**

Reel Dimension:



## PRECAUTIONS OF USE:

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### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

### Baking:

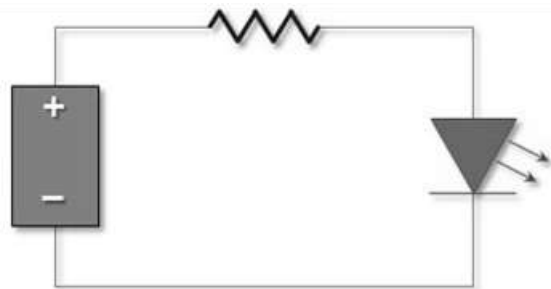
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



**REVISION RECORD:**

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Version	Date	Summary of Revision
A1.0	03/07/2014	Datasheet set-up.
A1.1	16/07/2014	Revise picture and specification.
A1.2	13/03/2015	Revise picture.
A1.3	16/03/2015	P/N add suffix RV indicating Reverse Mount.